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Details

Product Status	Active
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	I ² C, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	23
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	28-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s08sh16ctl

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



Chapter 1 Device Overview

1.3 System Clock Distribution

Figure 1-2 shows a simplified clock connection diagram. Some modules in the MCU have selectable clock inputs as shown. The clock inputs to the modules indicate the clock(s) that are used to drive the module function.

The following defines the clocks used in this MCU:

- BUSCLK The frequency of the bus is always half of ICSOUT.
- ICSOUT Primary output of the ICS and is twice the bus frequency.
- ICSLCLK Development tools can select this clock source to speed up BDC communications in systems where the bus clock is configured to run at a very slow frequency.
- ICSERCLK External reference clock can be selected as the RTC clock source and as the alternate clock for the ADC module.
- ICSIRCLK Internal reference clock can be selected as the RTC clock source.
- ICSFFCLK Fixed frequency clock can be selected as clock source for the TPM1, TPM2 and MTIM modules.
- LPOCLK Independent 1-kHz clock source that can be selected as the clock source for the COP and RTC modules.
- TCLK External input clock source for TPM1, TPM2 and MTIM and is referenced as TPMCLK in TPM chapters.



Figure 1-2. System Clock Distribution Diagram

MC9S08SH32 Series Data Sheet, Rev. 3



2.2.3 **RESET**

After a power-on reset (POR), the PTA5/IRQ/TCLK/RESET pin defaults to a general-purpose I/O port pin, PTA5. Setting RSTPE in SOPT1 configures the pin to be the RESET pin with an open-drain drive containing an internal pull-up device. After configured as RESET, the pin will remain RESET until the next POR. The RESET pin when enabled can be used to reset the MCU from an external source when the pin is driven low.

Internal power-on reset and low-voltage reset circuitry typically make external reset circuitry unnecessary. This pin is normally connected to the standard 6-pin background debug connector so a development system can directly reset the MCU system. If desired, a manual external reset can be added by supplying a simple switch to ground (pull reset pin low to force a reset).

Whenever any non-POR reset is initiated (whether from an external signal or from an internal system), the $\overline{\text{RESET}}$ pin if enabled is driven low for about 66 bus cycles. The reset circuitry decodes the cause of reset and records it by setting a corresponding bit in the system reset status register (SRS).

NOTE

This pin does not contain a clamp diode to V_{DD} and should not be driven above V_{DD} .

The voltage measured on the internally pulled up $\overline{\text{RESET}}$ pin will not be pulled to V_{DD} . The internal gates connected to this pin are pulled to V_{DD} . If the $\overline{\text{RESET}}$ pin is required to drive to a V_{DD} level an external pullup should be used.

NOTE

In EMC-sensitive applications, an external RC filter is recommended on the $\overline{\text{RESET}}$ pin. See Figure 2-4 for an example.

2.2.4 Background / Mode Select (BKGD/MS)

During a power-on-reset (POR) or background debug force reset (see Section 5.7.3, "System Background Debug Force Reset Register (SBDFR)," for more information), the PTA4/ACMPO/BKGD/MS pin functions as a mode select pin. Immediately after any reset, the pin functions as the background pin and can be used for background debug communication. When enabled as the BKGD/MS pin (BKGDPE = 1), an internal pullup device is automatically enabled.

The background debug communication function is enabled when BKGDPE in SOPT1 is set. BKGDPE is set following any reset of the MCU and must be cleared to use the PTA4/ACMPO/BKGD/MS pin's alternative pin function.

If nothing is connected to this pin, the MCU will enter normal operating mode at the rising edge of the internal reset after a POR or force BDC reset. If a debug system is connected to the 6-pin standard background debug header, it can hold BKGD/MS low during a POR or immediately after issuing a background debug force reset, which will force the MCU to active background mode.



Chapter 4 Memory

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0x00 66	TPM2C0VH	Bit 15	14	13	12	11	10	9	Bit 8
0x00 67	TPM2C0VL	Bit 7	6	5	4	3	2	1	Bit 0
0x00 68	TPM2C1SC	CH1F	CH1IE	MS1B	MS1A	ELS1B	ELS1A	0	0
0x00 69	TPM2C1VH	Bit 15	14	13	12	11	10	9	Bit 8
0x00 6A	TPM2C1VL	Bit 7	6	5	4	3	2	1	Bit 0
0x00 6B	Reserved	—		_	_	_		_	—
0x00 6C	RTCSC	RTIF	RTCLKS RTIE RTCPS						
0x00 6D	RTCCNT	RTCCNT							
0x00 6E	RTCMOD	RTCMOD							
0x00 6F - 0x00 7F	Reserved			_	_	_	—	_	—



Chapter 4 Memory

The first byte of a series of sequential bytes being programmed in burst mode will take the same amount of time to program as a byte programmed in standard mode. Subsequent bytes will program in the burst program time provided that the conditions above are met. In the case the next sequential address is the beginning of a new row, the program time for that byte will be the standard time instead of the burst time. This is because the high voltage to the array must be disabled and then enabled again. If a new burst command has not been queued before the current command completes, then the charge pump will be disabled and high voltage removed from the array.



MC9S08SH32 Series Data Sheet, Rev. 3



must be programmed to logic 0 to enable block protection. Therefore the value 0xF8 must be programmed into NVPROT to protect addresses 0xFA00 through 0xFFFF.



Figure 4-4. Block Protection Mechanism

One use for block protection is to block protect an area of FLASH memory for a bootloader program. This bootloader program then can be used to erase the rest of the FLASH memory and reprogram it. Because the bootloader is protected, it remains intact even if MCU power is lost in the middle of an erase and reprogram operation.

4.5.7 Vector Redirection

Whenever any block protection is enabled, the reset and interrupt vectors will be protected. Vector redirection allows users to modify interrupt vector information without unprotecting bootloader and reset vector space. Vector redirection is enabled by programming the FNORED bit in the NVOPT register located at address 0xFFBF to zero. For redirection to occur, at least some portion but not all of the FLASH memory must be block protected by programming the NVPROT register located at address 0xFFBD. All of the interrupt vectors (memory locations 0xFFC0–0xFFFD) are redirected, though the reset vector (0xFFFE:FFFF) is not.

For example, if 512 bytes of FLASH are protected, the protected address region is from 0xFE00 through 0xFFFF. The interrupt vectors (0xFFC0–0xFFFD) are redirected to the locations 0xFDC0–0xFDFD. Now, if an SPI interrupt is taken for instance, the values in the locations 0xFDE0:FDE1 are used for the vector instead of the values in the locations 0xFFE0:FFE1. This allows the user to reprogram the unprotected portion of the FLASH with new program code including new interrupt vector values while leaving the protected area, which includes the default vector locations, unchanged.

4.6 Security

The MC9S08SH32 Series includes circuitry to prevent unauthorized access to the contents of FLASH and RAM memory. When security is engaged, FLASH and RAM are considered secure resources. Direct-page registers, high-page registers, and the background debug controller are considered unsecured resources. Programs executing within secure memory have normal access to any MCU memory locations and resources. Attempts to access a secure memory location with a program executing from an unsecured memory space or through the background debug interface are blocked (writes are ignored and reads return all 0s).

Security is engaged or disengaged based on the state of two nonvolatile register bits (SEC01:SEC00) in the FOPT register. During reset, the contents of the nonvolatile location NVOPT are copied from FLASH into the working FOPT register in high-page register space. A user engages security by programming the NVOPT location which can be done at the same time the FLASH memory is programmed. The 1:0 state disengages security and the other three combinations engage security. Notice the erased state (1:1) makes



5.7.2 System Reset Status Register (SRS)

This high page register includes read-only status flags to indicate the source of the most recent reset. When a debug host forces reset by writing 1 to BDFR in the SBDFR register, none of the status bits in SRS will be set. Writing any value to this register address causes a COP reset when the COP is enabled except the values 0x55 and 0xAA. Writing a 0x55-0xAA sequence to this address clears the COP watchdog timer without affecting the contents of this register. The reset state of these bits depends on what caused the MCU to reset.

	7	6	5	4	3	2	1	0
R	POR	PIN	COP	ILOP	ILAD	0	LVD	0
w		Wr	iting 0x55, 0xA	A to SRS addr	ess clears CO	vatchdog tim	ier.	
POR:	1	0	0	0	0	0	1	0
LVR:	u ¹	0	0	0	0	0	1	0
Any other reset:	0	Note ²	Note ²	Note ²	Note ²	0	0	0

¹ u = unaffected

² Any of these reset sources that are active at the time of reset entry will cause the corresponding bit(s) to be set; bits corresponding to sources that are not active at the time of reset entry will be cleared.

Figure 5-3. System Reset Status (SRS)

Table 5-4. SRS Register Field Descriptions

Field	Description
7 POR	 Power-On Reset — Reset was caused by the power-on detection logic. Because the internal supply voltage was ramping up at the time, the low-voltage reset (LVD) status bit is also set to indicate that the reset occurred while the internal supply was below the LVD threshold. 0 Reset not caused by POR. 1 POR caused reset.
6 PIN	 External Reset Pin — Reset was caused by an active-low level on the external reset pin. 0 Reset not caused by external reset pin. 1 Reset came from external reset pin.
5 COP	 Computer Operating Properly (COP) Watchdog — Reset was caused by the COP watchdog timer timing out. This reset source can be blocked by COPE = 0. 0 Reset not caused by COP timeout. 1 Reset caused by COP timeout.
4 ILOP	 Illegal Opcode — Reset was caused by an attempt to execute an unimplemented or illegal opcode. The STOP instruction is considered illegal if stop is disabled by STOPE = 0 in the SOPT register. The BGND instruction is considered illegal if active background mode is disabled by ENBDM = 0 in the BDCSC register. 0 Reset not caused by an illegal opcode. 1 Reset caused by an illegal opcode.



6.6.1 Port A Registers

Port A is controlled by the registers listed below.

The pins PTA4 and PTA5 are unique. PTA4 is output-only, so the control bits for the input function will not have any effect on this pin. PTA5, when configured as an output, is open drain.

NOTE

This PTA5 pin does not contain a clamp diode to V_{DD} and should not be driven above $V_{DD}.$

When the internal pullup device is enabled on PTA5 when used as an input or open drain output the voltage measured on PTA5 will not be pulled to V_{DD} . The internal gates connected to this pin are pulled to V_{DD} . If the PTA5 pin is required to drive to a V_{DD} level an external pullup should be used.

6.6.1.1 Port A Data Register (PTAD)

_	7	6	5	4	3	2	1	0
R	PTAD7	PTAD6	PTAD5	PTAD4 ¹	PTAD3	PTAD2	PTAD1	PTAD0
vv								
Reset:	0	0	0	0	0	0	0	0

Figure 6-3. Port A Data Register (PTAD)

¹ Reads of bit PTAD4 always return the contents of PTAD4, regardless of the value stored in bit PTADD4.

Table 6-2. PTAD Register Field Descriptions

Field	Description
7:0 PTAD[7:0]	Port A Data Register Bits — For port A pins that are inputs, reads return the logic level on the pin. For port A pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port A pins that are configured as outputs, the logic level is driven out the corresponding MCU pin. Reset forces PTAD to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pull-ups/pull-downs disabled.

Chapter 9 Analog-to-Digital Converter (S08ADCV1)



Figure 9-3. St	tatus and C	Control Registe	er (ADCSC1)
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Table 9-3.	ADCSC1	Register	Field	Descriptions
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Field	Description
7 COCO	Conversion Complete Flag — The COCO flag is a read-only bit which is set each time a conversion is completed when the compare function is disabled (ACFE = 0). When the compare function is enabled (ACFE = 1) the COCO flag is set upon completion of a conversion only if the compare result is true. This bit is cleared whenever ADCSC1 is written or whenever ADCRL is read. 0 Conversion not completed 1 Conversion completed
6 AIEN	 Interrupt Enable — AIEN is used to enable conversion complete interrupts. When COCO becomes set while AIEN is high, an interrupt is asserted. 0 Conversion complete interrupt disabled 1 Conversion complete interrupt enabled
5 ADCO	 Continuous Conversion Enable — ADCO is used to enable continuous conversions. One conversion following a write to the ADCSC1 when software triggered operation is selected, or one conversion following assertion of ADHWT when hardware triggered operation is selected. Continuous conversions initiated following a write to ADCSC1 when software triggered operation is selected. Continuous conversions are initiated by an ADHWT event when hardware triggered operation is selected.
4:0 ADCH	Input Channel Select — The ADCH bits form a 5-bit field which is used to select one of the input channels. The input channels are detailed in Figure 9-4. The successive approximation converter subsystem is turned off when the channel select bits are all set to 1. This feature allows for explicit disabling of the ADC and isolation of the input channel from all sources. Terminating continuous conversions this way will prevent an additional, single conversion from being performed. It is not necessary to set the channel select bits to all 1s to place the ADC in a low-power state when continuous conversion are not enabled because the module automatically enters a low-power state when a conversion completes.

Figure 9-4. Input Channel Select

ADCH	Input Select
00000	AD0
00001	AD1
00010	AD2
00011	AD3
00100	AD4
00101	AD5
00110	AD6
00111	AD7

Input Select
AD16
AD17
AD18
AD19
AD20
AD21
AD22
AD23



9.4.7.2 Stop3 Mode With ADACK Enabled

If ADACK is selected as the conversion clock, the ADC continues operation during stop3 mode. For guaranteed ADC operation, the MCU's voltage regulator must remain active during stop3 mode. Consult the module introduction for configuration information for this MCU.

If a conversion is in progress when the MCU enters stop3 mode, it continues until completion. Conversions can be initiated while the MCU is in stop3 mode by means of the hardware trigger or if continuous conversions are enabled.

A conversion complete event sets the COCO and generates an ADC interrupt to wake the MCU from stop3 mode if the ADC interrupt is enabled (AIEN = 1).

NOTE

It is possible for the ADC module to wake the system from low power stop and cause the MCU to begin consuming run-level currents without generating a system level interrupt. To prevent this scenario, software should ensure that the data transfer blocking mechanism (discussed in Section 9.4.4.2, "Completing Conversions) is cleared when entering stop3 and continuing ADC conversions.

9.4.8 MCU Stop1 and Stop2 Mode Operation

The ADC module is automatically disabled when the MCU enters either stop1 or stop2 mode. All module registers contain their reset values following exit from stop1 or stop2. Therefore the module must be re-enabled and re-configured following exit from stop1 or stop2.

9.5 Initialization Information

This section gives an example which provides some basic direction on how a user would initialize and configure the ADC module. The user has the flexibility of choosing between configuring the module for 8-bit or 10-bit resolution, single or continuous conversion, and a polled or interrupt approach, among many other options. Refer to Table 9-6, Table 9-7, and Table 9-8 for information used in this example.

NOTE

Hexadecimal values designated by a preceding 0x, binary values designated by a preceding %, and decimal values have no preceding character.

9.5.1 ADC Module Initialization Example

9.5.1.1 Initialization Sequence

Before the ADC module can be used to complete conversions, an initialization procedure must be performed. A typical sequence is as follows:

1. Update the configuration register (ADCCFG) to select the input clock source and the divide ratio used to generate the internal clock, ADCK. This register is also used for selecting sample time and low-power configuration.





10.4 Functional Description

This section provides a complete functional description of the IIC module.

10.4.1 IIC Protocol

The IIC bus system uses a serial data line (SDA) and a serial clock line (SCL) for data transfer. All devices connected to it must have open drain or open collector outputs. A logic AND function is exercised on both lines with external pullup resistors. The value of these resistors is system dependent.

Normally, a standard communication is composed of four parts:

- Start signal
- Slave address transmission
- Data transfer
- Stop signal

The stop signal should not be confused with the CPU stop instruction. The IIC bus system communication is described briefly in the following sections and illustrated in Figure 10-9.



Figure 10-9. IIC Bus Transmission Signals

10.4.1.1 Start Signal

When the bus is free, no master device is engaging the bus (SCL and SDA lines are at logical high), a master may initiate communication by sending a start signal. As shown in Figure 10-9, a start signal is defined as a high-to-low transition of SDA while SCL is high. This signal denotes the beginning of a new data transfer (each data transfer may contain several bytes of data) and brings all slaves out of their idle states.



Chapter 12 Modulo Timer (S08MTIMV1)

12.1 Introduction

The MTIM is a simple 8-bit timer with several software selectable clock sources and a programmable interrupt.

The central component of the MTIM is the 8-bit counter, which can operate as a free-running counter or a modulo counter. A timer overflow interrupt can be enabled to generate periodic interrupts for time-based software loops.

Figure 12-1 shows the MC9S08SH32 Series block diagram with the MTIM highlighted.

12.1.1 MTIM Configuration Information

The external clock for the MTIM module, TCLK, is selected by setting CLKS = 1:1 or 1:0 in MTIMCLK, which selects the TCLK pin input. The TCLK input can be enabled as external clock inputs to both the MTIM and TPM modules simultaneously.



12.4 Functional Description

The MTIM is composed of a main 8-bit up-counter with an 8-bit modulo register, a clock source selector, and a prescaler block with nine selectable values. The module also contains software selectable interrupt logic.

The MTIM counter (MTIMCNT) has three modes of operation: stopped, free-running, and modulo. Out of reset, the counter is stopped. If the counter is started without writing a new value to the modulo register, then the counter will be in free-running mode. The counter is in modulo mode when a value other than \$00 is in the modulo register while the counter is running.

After any MCU reset, the counter is stopped and reset to \$00, and the modulus is set to \$00. The bus clock is selected as the default clock source and the prescale value is divide by 1. To start the MTIM in free-running mode, simply write to the MTIM status and control register (MTIMSC) and clear the MTIM stop bit (TSTP).

Four clock sources are software selectable: the internal bus clock, the fixed frequency clock (XCLK), and an external clock on the TCLK pin, selectable as incrementing on either rising or falling edges. The MTIM clock select bits (CLKS1:CLKS0) in MTIMSC are used to select the desired clock source. If the counter is active (TSTP = 0) when a new clock source is selected, the counter will continue counting from the previous value using the new clock source.

Nine prescale values are software selectable: clock source divided by 1, 2, 4, 8, 16, 32, 64, 128, or 256. The prescaler select bits (PS[3:0]) in MTIMSC select the desired prescale value. If the counter is active (TSTP = 0) when a new prescaler value is selected, the counter will continue counting from the previous value using the new prescaler value.

The MTIM modulo register (MTIMMOD) allows the overflow compare value to be set to any value from \$01 to \$FF. Reset clears the modulo value to \$00, which results in a free running counter.

When the counter is active (TSTP = 0), the counter increments at the selected rate until the count matches the modulo value. When these values match, the counter overflows to \$00 and continues counting. The MTIM overflow flag (TOF) is set whenever the counter overflows. The flag sets on the transition from the modulo value to \$00. Writing to MTIMMOD while the counter is active resets the counter to \$00 and clears TOF.

Clearing TOF is a two-step process. The first step is to read the MTIMSC register while TOF is set. The second step is to write a 0 to TOF. If another overflow occurs between the first and second steps, the clearing process is reset and TOF will remain set after the second step is performed. This will prevent the second occurrence from being missed. TOF is also cleared when a 1 is written to TRST or when any value is written to the MTIMMOD register.

The MTIM allows for an optional interrupt to be generated whenever TOF is set. To enable the MTIM overflow interrupt, set the MTIM overflow interrupt enable bit (TOIE) in MTIMSC. TOIE should never be written to a 1 while TOF = 1. Instead, TOF should be cleared first, then the TOIE can be set to 1.



Chapter 14 Serial Communications Interface (S08SCIV4)

14.1.3 Block Diagram

Figure 14-2 shows the transmitter portion of the SCI.



Figure 14-2. SCI Transmitter Block Diagram



15.5.2 SPI Interrupts

There are three flag bits, two interrupt mask bits, and one interrupt vector associated with the SPI system. The SPI interrupt enable mask (SPIE) enables interrupts from the SPI receiver full flag (SPRF) and mode fault flag (MODF). The SPI transmit interrupt enable mask (SPTIE) enables interrupts from the SPI transmit buffer empty flag (SPTEF). When one of the flag bits is set, and the associated interrupt mask bit is set, a hardware interrupt request is sent to the CPU. If the interrupt mask bits are cleared, software can poll the associated flag bits instead of using interrupts. The SPI interrupt service routine (ISR) should check the flag bits to determine what event caused the interrupt. The service routine should also clear the flag bit(s) before returning from the ISR (usually near the beginning of the ISR).

15.5.3 Mode Fault Detection

A mode fault occurs and the mode fault flag (MODF) becomes set when a master SPI device detects an error on the \overline{SS} pin (provided the \overline{SS} pin is configured as the mode fault input signal). The \overline{SS} pin is configured to be the mode fault input signal when MSTR = 1, mode fault enable is set (MODFEN = 1), and slave select output enable is clear (SSOE = 0).

The mode fault detection feature can be used in a system where more than one SPI device might become a master at the same time. The error is detected when a master's \overline{SS} pin is low, indicating that some other SPI device is trying to address this master as if it were a slave. This could indicate a harmful output driver conflict, so the mode fault logic is designed to disable all SPI output drivers when such an error is detected.

When a mode fault is detected, MODF is set and MSTR is cleared to change the SPI configuration back to slave mode. The output drivers on the SPSCK, MOSI, and MISO (if not bidirectional mode) are disabled.

MODF is cleared by reading it while it is set, then writing to the SPI control register 1 (SPIxC1). User software should verify the error condition has been corrected before changing the SPI back to master mode.



Chapter 16 Timer/PWM Module (S08TPMV3)



Figure 16-2. TPM Block Diagram



Chapter 17 Development Support

17.2.3 BDC Commands

BDC commands are sent serially from a host computer to the BKGD pin of the target HCS08 MCU. All commands and data are sent MSB-first using a custom BDC communications protocol. Active background mode commands require that the target MCU is currently in the active background mode while non-intrusive commands may be issued at any time whether the target MCU is in active background mode or running a user application program.

Table 17-1 shows all HCS08 BDC commands, a shorthand description of their coding structure, and the meaning of each command.

Coding Structure Nomenclature

This nomenclature is used in Table 17-1 to describe the coding structure of the BDC commands.

Commands begin with an 8-bit hexadecimal command code in the host-to-target direction (most significant bit first)

- / = separates parts of the command
- d = delay 16 target BDC clock cycles
- AAAA = a 16-bit address in the host-to-target direction
 - RD = 8 bits of read data in the target-to-host direction
 - WD = 8 bits of write data in the host-to-target direction
- RD16 = 16 bits of read data in the target-to-host direction
- WD16 = 16 bits of write data in the host-to-target direction
 - SS = the contents of BDCSCR in the target-to-host direction (STATUS)
 - CC = 8 bits of write data for BDCSCR in the host-to-target direction (CONTROL)
- RBKP = 16 bits of read data in the target-to-host direction (from BDCBKPT breakpoint register)
- WBKP = 16 bits of write data in the host-to-target direction (for BDCBKPT breakpoint register)



Appendix A Electrical Characteristics

The average chip-junction temperature (T_J) in °C can be obtained from:

$$T_{J} = T_{A} + (P_{D} \times \theta_{JA})$$
 Eqn. A-1

where:

$$\begin{split} T_A &= \text{Ambient temperature, } ^{\circ}\text{C} \\ \theta_{JA} &= \text{Package thermal resistance, junction-to-ambient, } ^{\circ}\text{C/W} \\ P_D &= P_{int} + P_{I/O} \\ P_{int} &= I_{DD} \times V_{DD}, \text{Watts } \text{ -- chip internal power} \\ P_{I/O} &= \text{Power dissipation on input and output pins } \text{ -- user determined} \end{split}$$

For most applications, $P_{I/O} \ll P_{int}$ and can be neglected. An approximate relationship between P_D and T_J (if $P_{I/O}$ is neglected) is:

$$P_{D} = K \div (T_{J} + 273^{\circ}C)$$
 Eqn. A-2

Solving Equation A-1 and Equation A-2 for K gives:

$$K = P_D \times (T_A + 273^{\circ}C) + \theta_{JA} \times (P_D)^2$$
 Eqn. A-3

where K is a constant pertaining to the particular part. K can be determined from equation 3 by measuring P_D (at equilibrium) for a known T_A . Using this value of K, the values of P_D and T_J can be obtained by solving Equation A-1 and Equation A-2 iteratively for any value of T_A .



Appendix A Electrical Characteristics

A.7 Supply Current Characteristics

This section includes information about power supply current in various operating modes.

#	с	Parameter	Symbol	V _{DD} (V)	Typ ¹	Max ²	Unit			
1	С	Run supply current measured at		5	1.4	3	mA			
	С	(CPU clock = 4 MHz, f _{Bus} = 2 MHz)	RI _{DD}	3	1.3	2.5	mA			
2	Р	Run supply current ³ measured at		5	4.7	7.5	mA			
	С	(CPU clock = 16 MHz, f _{Bus} = 8 MHz)	RI _{DD}	3	4.6	7	mA			
3	С	Run supply current measured at		5	8.9	10	mA			
	С	(CPU clock = 32 MHz, f _{Bus} = 16MHz)	RI _{DD}	3	8.7	9.6	mA			
		Stop3 mode supply current								
		–40°C (C and M suffix)		5	0.96	-	μA			
4	Р	25°C (All parts)			1.3	-	μA			
	P ⁵	85°C (C suffix only)			16.9	35	μA			
	P ⁵	125°C (M suffix only) S3I _{DD} -40°C (C and M suffix)			84	150	μA			
	С				0.85	-	μA			
	Р	25°C (All parts)		3	1.2	-	μΑ			
	P ⁵	85°C (C suffix only)			14.8	30	μA			
	P ⁵	125°C (M suffix only)			75	130	μA			

Table A-7. Supply Current Characteristics



Appendix A Electrical Characteristics

A.11 ADC Characteristics

Table A-11. ADC Operating Conditions

#	Characteristic	Conditions	Symb	Min	Typ ¹	Max	Unit	Comment
1	Supply voltage	Absolute	V _{DDAD}	2.7	—	5.5	V	
2	Input Voltage		V _{ADIN}	V _{REFL}	_	V _{REF} H	v	
3	Input Capacitance		C _{ADIN}	_	4.5	5.5	pF	
4	Input Resistance		R _{ADIN}	_	3	5	kΩ	
5	Analog Source Resistance	10 bit mode f _{ADCK} > 4MHz f _{ADCK} < 4MHz	R _{AS}	_	_	5 10	kΩ	External to MCU
		8 bit mode (all valid f _{ADCK})		_	_	10	kΩ	
6	ADC Conversion Clock Freq.	High Speed (ADLPC=0)	f _{ADCK}	0.4	—	8.0	MHz	
		Low Power (ADLPC=1)		0.4	_	4.0	MHz	

¹ Typical values assume V_{DDAD} = V_{DD} = 5.0V, Temp = 25°C, f_{ADCK}=1.0MHz unless otherwise stated. Typical values are for reference only and are not tested in production.



Figure A-9. ADC Input Impedance Equivalency Diagram

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#	Characteristic	Conditions	С	Symb	Min	Typ ¹	Max	Unit	Comment
1	Supply current	ADLPC=1 ADLSMP=1 ADCO=1	т	I _{DD} + I _{DDAD}	_	133	_	μΑ	ADC current only
		ADLPC=1 ADLSMP=0 ADCO=1	т	I _{DD} + I _{DDAD}	_	218	_	μΑ	ADC current only
		ADLPC=0 ADLSMP=1 ADCO=1	т	I _{DD} + I _{DDAD}	_	327	_	μA	ADC current only
		ADLPC=0 ADLSMP=0 ADCO=1	Ρ	I _{DD} + I _{DDAD}	_	0.58 2	1	mA	ADC current only
	ADC asynchronous clock source	High speed (ADLPC=0)	Р	f _{ADACK}	2	3.3	5	MHz	t _{adack} = 1/f _{adack}
2		Low power (ADLPC=1)			1.25	2	3.3		
3	Conversion time (including sample time)	Short sample (ADLSMP=0)	D	t _{ADC}		20		ADCK cycles	See ADC Chapter for conversion time variances
		Long sample (ADLSMP=1)			—	40	—		
4	Sample time	Short sample (ADLSMP=0)	- D	t _{ADS}	_	3.5	_	ADCK cycles	
		Long sample (ADLSMP=1)			_	23.5	_		
		28-pin packages only							
	Total	10-bit mode	Р	E _{TUE}	_	±1	±2.5	LSB ²	
	error (includes quantization)	8-bit mode				±0.5	±1		
5		20-pin packages							
		10-bit mode	P	E _{TUE}	_	±.5	±3.5	LSB ²	
		8-bit mode			_	±0.7	±1.5		
		16-pin packages							
		10-bit mode	P	E _{TUE}	_	±.5	±3.5	LSB ²	
		8-bit mode			_	±0.7	±1.5		